

Program Overview

Wednesday 10 October		
	MAP	RTS
13:00 ~ 13:10	Opening Remark	POSTER & EXHIBITION
13:10 ~ 14:40	SESSION 1: Invited Talks	
14:40 ~ 15:00	COFFEE BREAK	
15:00 ~ 16:00	SESSION 2: JEITA Program	
16:00 ~ 16:20	COFFEE BREAK	
16:20 ~ 18:00	SESSION 3: ICT Symposium - Technology for Next Generation Electric Vehicle -	
18:30 ~ 20:00	RECEPTION PARTY (Flamingo Café 3F)	
Thursday 11 October		
09:00 ~ 10:15	SESSION 4: Design for Manufacturability	POSTER & EXHIBITION
10:15 ~ 10:35	COFFEE BREAK	
10:35 ~ 12:20	SESSION 5: Tool, Test and Business Proposal	
12:20 ~ 12:45	LUNCH BREAK	
12:45 ~ 14:45	SESSION 6: Advanced Packaging Technology	
14:45 ~ 15:05	COFFEE BREAK	
15:05 ~ 16:50	SESSION 7: Substrate and Interconnection Materials	
17:00 ~ 18:30	SESSION 8: Poster Session and Exhibition with Wines	

MAP&RTS 2007 PROGRAM

Wednesday 10 October

13:00 ~ 13:10 Opening Remark

Hajime Tomokage
Fukuoka University (JAPAN)

13:10 ~ 14:40 SESSION 1: Invited Talks

Chair : Eddie Ohtsuru (Fukuoka Industry, Science & Technology Foundation)

**13:10~13:40 1.1 A Short Introduction about the Status of Semiconductor Industries
in Northern China**

Zihua WANG
Tsinghua University (CHINA)

**13:40~14:10 1.2 Development of Evaluation Software for System LSI Collaborating
with Chinese University**

Hirokazu Tanaka
Hokkaido University (JAPAN)

**14:10~14:40 1.3 Tera Probe, New Test Business Partner as Value Added Solution
Provider**

Masahide Ozawa
Tera Probe, Inc. (JAPAN)

14:40 ~ 15:00 COFFEE BREAK

15:00 ~ 16:00 SESSION 2 : JEITA Program

Chair: Fumiaki Shigeoka (Ueno Seiki Co., Ltd.)

15:00~15:30 2.1 Mobile Products Trend and Requirement to Semiconductor Package

Hiroshi Manita
Casio Computer Co., LTD. (JAPAN)

**15:30~16:00 2.2 Challenges of Semiconductor Packaging Technologies to Meet the
Requirements from Electronics Products**

-From Japan Jisso Technology Roadmap 2007-
Shoji Uegaki
ASE Marketing & Service Japan Co., Ltd. (JAPAN)

16:00 ~ 16:20 COFFEE BREAK

16:20 ~ 18:00 **SESSION 3: ICT Symposium**
- Technology for Next Generation Electric Vehicle -
Chair : Hajime Tomokage (Fukuoka University)

16:20~17:00 **3.1 Concept and Technology of Next Generation Electric Vehicle (Eliica)**
Hiroshi Shimizu
Keio University (JAPAN)

17:00~17:20 **3.2 Future Personal Mobility “i-unit”**
Makoto Morita
TOYOTA MOTOR CORPORATION (JAPAN)

17:20~17:40 **3.3 Technological Requirements for Electric Vehicles and Kyushu Electric’s Efforts for Their Promotion**
K. Kazuyuki, S. Murakami, Y. Wada, H. Shibata and K. Kurayama
Kyushu Electric Power Co., Inc. (JAPAN)

17:40~18:00 **3.4 Trends for Car Electronics Market and Testing Equipment**
Yasunori Yamaguchi
TERADYNE (JAPAN)

18:30 ~ 20:00 **RECEPTION PARTY (Flamingo Café, 3F)**

Thursday 11 October

09:00 ~10:15 **SESSION 4: Design for Manufacturability (DFM)**
Chair : Joseph Fjelstad (Sillicon Pipe, Inc.)

09:00~09:15 **4.1 Jisso Technology Trends – Why DFM is necessary ?**
Kazunori Kato
Advanced Interface Technology Corp. (JAPAN)

09:15~09:30 **4.2 DFM System for Final Manufacturing of LSI**
Andres Carrasco
Nagase Electronic Equipment Service Co., Ltd. (JAPAN)

09:30~09:45 **4.3 An Integrated Design & Analysis Solution for Advanced IC Package and System-in-Package (SiP) Design**
Dave DeMaria
Optimal Corp. (U.S.A.)

- 09:45~10:00 4.4 Practical Use of Package Virtual Design System (PVDS) in Spansion**
Naomi Masuda, Ryota Fukuyama, Kouichi Meguro, Junichi Kasai
Spansion Japan Limited (JAPAN)
- 10:00~10:15 4.5 Ideal DFM for Backend Business in Japanese LSI Industry**
Ichiro Anjo
Akita Elpida Memory Inc. (JAPAN)

10:15 ~ 10:35	COFFEE BREAK
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10:35 ~ 12:20 SESSION 5: Tool, Test and Business Proposal

Chair : Todd Takaki (Inoueki Co.,Ltd.)

- 10:35~10:50 5.1 EDA Tool for IC Packaging with Three Dimensions Database**
Hiroyuki Kataoka, Hidemichi Kawase* and Hajime Tomokage**
*HIBIKINO SYSTEM-LAB INC., *Keirex Technology and
**Fukuoka University (JAPAN)*
- 10:50~11:05 5.2 Tools of Semiconductor**
K.H.Cheon
EPULLER INDUSTRIAL PROJECT (KOREA)
- 11:05~11:20 5.3 The Auto Deprocessor and Power Voltage Sag Protector**
Mark K. Choi
Frontier Semiconductor (U.S.A.)
- 11:20~11:35 5.4 A Transition Delay Test Generation Method for Capture Power Reduction during At-Speed Scan Testing**
T. Fukuzawa, K.Miyase, Y.Yamato, H.Furukawa, X.Wen and S.Kajihara
Kyushu Institute of Technology (JAPAN)
- 11:35~11:50 5.5 KYEC's Japan Market Strategy -King Yuan Electronics Co., LTD. (KYEC)**
Toshio Sugano
King Yuan Electronics Co., LTD. (TAIWAN)
- 11:50~12:05 5.6 VIETNAM : A New Frontier for Electronics**
Hiroyasu Furusho and Seiichi Shikata*
*Inoueki Co.,Ltd. and *Sankyu Inc. (JAPAN)*
- 12:05~12:20 5.7 Successful Business Model for Cross-Border Collaboration**
P.Bala
FTD Technology PTE Ltd. (Singapore)

12:20 ~ 12:45 LUNCH BREAK

12:45 ~ 14:45 SESSION 6: Advanced Packaging Technology

Chair : Jae-Ho Lee (Hongik University)

- 12:45~13:00 6.1 Properties of Blue Light Emitting Diodes Using PFO-poss**
Su-Cheol Gong, Sang-Baie Shin, Ji-Keun Chang, Young-Chul Chang* and Ho-Jung Chang
*Dankook University and *Korea University of Technology and Education (KOREA)*
- 13:00~13:15 6.2 Unique IC and LED Packaging Technology**
A.OKUNO
SANYU REC CO., LTD. (JAPAN)
- 13:15~13:30 6.3 The ESC family for Mass Production Flip-Chip Process**
Koji Motomura, Seiichi Yoshinaga, Hideki Eifuku, Tadahiko Sakai and Shoji Sakemi
Panasonic Factory Solutions Co., Ltd. (JAPAN)
- 13:30~13:45 6.4 Laser Saw Development for Low-k Devices**
Mutsumi Masumoto
Texas Instruments Japan Limited (JAPAN)
- 13:45~14:00 6.5 Recent Advancement in Bonding Technology**
S. Wickramanayaka
EVGroup Japan KK (JAPAN)
- 14:00~14:15 6.6 Roll to Roll Printer System for Fine Pitch Patterning on PET Film Roll**
Hajime Fukawa
Produce Corp. (JAPAN)
- 14:15~14:30 6.7 SiP and st-MCP using Chip Stack Technology**
David Fang
Powertech Technology Inc. (TAIWAN)
- 14:30~14:45 6.8 Sn Through-Vias and Their Bumping Structures for Chip Stack Packages**
S.K.Kim, M.Y.Kim and T.S.Oh
Hongik University (KOREA)

14:45 ~ 15:05 COFFEE BREAK

- 15:05~ 16:50** **SESSION 7: Substrate and Interconnection Materials**
Chair : Yangdo Kim (Pusan National University)
- 15:05~15:20** **7.1 Directional Sintering in LTCC Substrate**
YONG-BIN SUN
Kyonggi University (KOREA)
- 15:20~15:35** **7.2 Newly Developed Halogen-free Materials for Package Substrate**
A.Hanawa, T.Kawai, K.Obata, T.Irino and K. Ikeda
Hitachi Chemical Co., Ltd.(JAPAN)
- 15:35~15:50** **7.3 Microstructure Characterization in the Au Stud-Pre-solder Flip Chip Joint**
Young-Min Kim, Young-Ho Kim, Woong Sun Lee* and Chul-ho Cho*
*Hanyang University and *Hynix Semiconductor Inc. (KOREA)*
- 15:50~16:05** **7.4 Newly Developed Isotropic Fabrication of LCP and its Application to Print Circuit Board**
S.Okamoto, T.Ito, Y.Kohinata, T.Abe and N.Takahashi
Sumitomo Chemical Co., Ltd. (JAPAN)
- 16:05~16:20** **7.5 The Effects of Bath Compositions on Copper Electroplating for the Defect-free Small Via Filling**
Suk-Eui Lee and Jae-Ho Lee
Hongik University (KOREA)
- 16:20~16:35** **7.6 Development of New Acrylic Based Thermal Interface Materials**
Takuo Suzuki, Tadahiro Takano and Mamoru Ubukata
Achilles Corporation (JAPAN)
- 16:35~16:50** **7.7 Fabrication of ZnS-SiO₂ Sputtering Target and its Properties**
Young Do Kim, Gil-Su Kim, Dae-Hoon Shin, Se-Hoon Kim, Hoon Cho* and Ki-Sung Park**
*Hanyang University, *Korea Institute of Industrial Technology and **Vaevac International Co.,Ltd. (KOREA)*
- 17:00 ~ 18:30** **SESSION 8: Poster Session and Exhibition with Wines**
Chair : Daisuke Yamaguchi (ATE Service Corporation)
- 8.1 Low Temperature Densification of Mo Nanopowder Prepared by Mechanochemical Process**
Hai Gon Kim, Gil-Su Kim, Seungho Lee, Young Jung Lee and Young Do Kim
Hanyang University (KOREA)

8.2 Densification of W-Cu Nanocomposite Powder Prepared by Mechanochemical Process

Seungho Lee, Se-Hoon Kim, Young Jung Lee, Young Ik Seo and Young Do Kim

Hanyang University (KOREA)